

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3524020

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KYONG-CHAN LIM	08/28/2015
RECEIVING PARTY DATA	
Name:	SEOUL LASER DIEBOARD SYSTEM CO., LTD
Street Address:	1029-30 HOGAE-DONG
Internal Address:	DONGAN-KU, ANYANG CITY
City:	KYUNGGIDO
State/Country:	KOREA, REPUBLIC OF
Name:	SEOUL LASER DIEBOARD SYSTEM CO., LTD LLP
Street Address:	10035 CARROLL CANYON BLVD.
Internal Address:	SUITE B
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92131
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14692591
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	619-238-1900
Email:	docketing@procopio.com
Correspondent Name:	PROCOPIO, CORY, HARGREAVES & SAVITCH
Address Line 1:	525 B STREET
Address Line 2:	SUITE 2200
Address Line 4:	SAN DIEGO, CALIFORNIA 92101
ATTORNEY DOCKET NUMBER:	113764-2017C3
NAME OF SUBMITTER:	JUDITH MORROW
SIGNATURE:	/Judith Morrow/

DATE SIGNED:	09/14/2015
Total Attachments: 1 source=1137642017C3.AssignmentsFiled#page1.tif	

ASSIGNMENT

WHEREAS, I, as a below named inventor, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in **PROFILES USED IN GENERATING CHANNEL LETTERS** (Application Number: 14/692,591, Filing Date: April 21, 2015).

AND WHEREAS, Seoul Laser Dieboard System Co., Ltd. a limited partnership with offices at 1029-30 Hogae-Dong, Dongen-ku, Anyang City, Kyunggido Republic of Korea and Seoul Laser Dieboard System Co., Ltd., a limited partnership, with offices at 10035 Carroll Canyon Boulevard, Suite B, San Diego, CA 92131 (hereinafter referred to as ASSIGNEES) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefore in the United States and in any and all foreign countries;

NOW THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, their successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any prior applications and any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or their designee(s), as ASSIGNEES or their successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at their own expense;

And I further agree that ASSIGNEES will, upon their request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

This assignment executed on the dates indicated below:

Kyong-Chan Lim
Name of first inventor

San Diego, California USA
Residence of first inventor


Signature of first inventor

Aug. 28th 2015
Date of Assignment